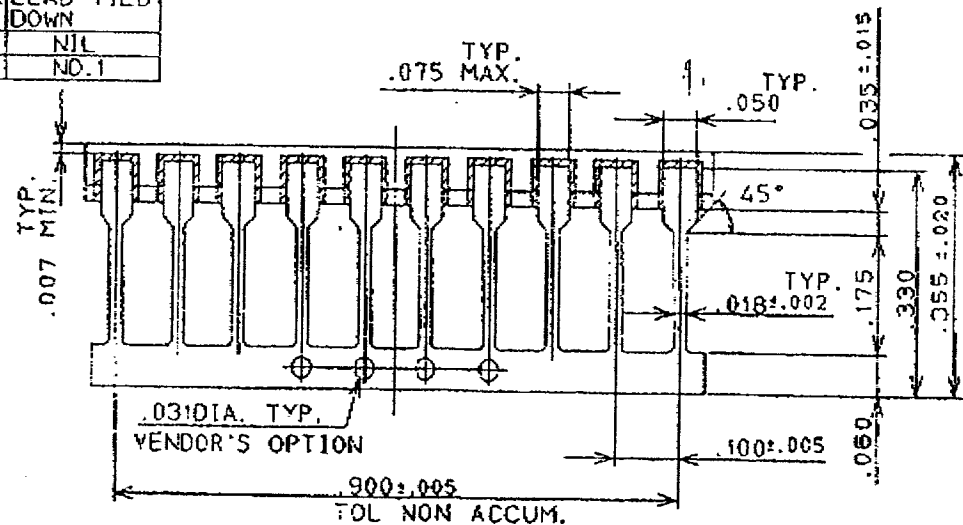


PART NO.	INDEX MARK	LEAD TIED DOWN
-01	⊙	NIL
-02	1	NO.1



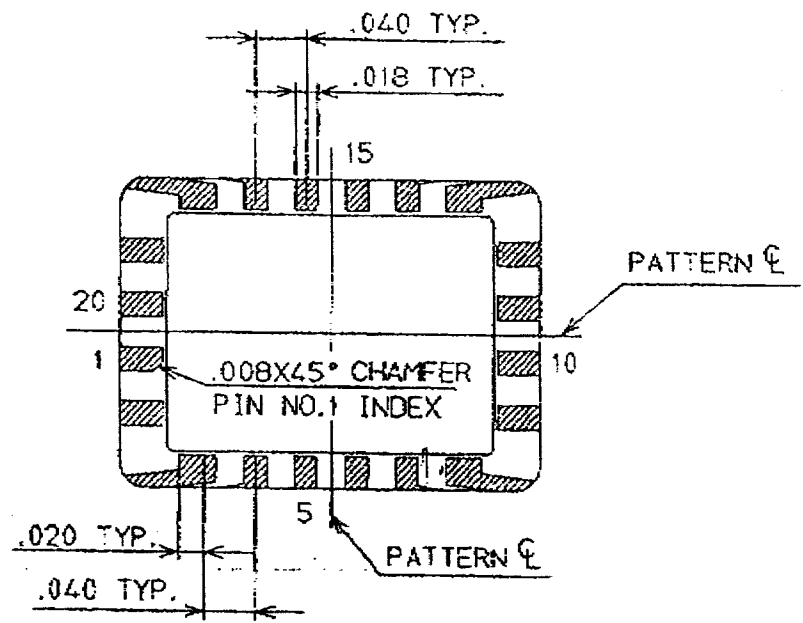
DETAIL - A

NOTES

1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
2. SEAL AREA TO BE METALLIZED.
3. DIE ATTACH AREA TO BE METALLIZED.
4. LEAD RESISTANCE : 0.3 Ω MAX.

SB020G250-2	S=0 D=1
SB020G250-1	S=0 D=0

MODIFICATION					NAME 20 LEAD SIDE BRAZED PACKAGE	TOLERANCE UNLESS OTHERWISE SPECIFIED	DRAWN M.S	CHECKED H.SU	APPROVED S.F T.A	DATE AUG.23.'96
					SCALE 5/1	MATERIAL AS INDICATED	±.005 WITH M2.2 PROJECTION	 DRAWING NO.		
	REDRAWN: (CONVERTED CAD DATA)	JUN 26 '95	M.S	H.SU						
	CHANGED	DATE	DRAWN	CHECKED	APPROVED	KYOCERA CORPORATION KYOTO JAPAN		DRAWING NO. KD-76250-C		SHEET 1/2



2/2

BONDING PATTERN

MODIFICATION					NAME 20 LEAD SIDE BRAZED PACKAGE	TOLERANCE UNLESS OTHERWISE SPECIFIED	DRAWN M.S	CHECKED H.SU S.F	APPROVED T.A	DATE AUG.23.76
					SCALE 10 / 1	MATERIAL				
						KYOCERA				
						KYOCERA CORPORATION KYOTO JAPAN				
	CHANGED	DATE	DRAWN	CHECKED	APPROVED			DRAWING NO. KD-76250-C		SHEET 2/2